

Title (en)
CONTACT PROBE DEVICE

Title (de)
KONTAKTSONDENEINRICHTUNG

Title (fr)
DISPOSITIF À SONDE DE CONTACT

Publication
EP 2282381 A4 20111012 (EN)

Application
EP 08777029 A 20080530

Priority
JP 2008060018 W 20080530

Abstract (en)
[origin: EP2282381A1] To obtain a satisfactory contact state in an ultra high frequency range with a low loss, in a contact probe device with an electronic component connected to a mounting substrate. Insulating substrate 1 has cuts 3 with narrow width formed from an outer peripheral end. Cylindrical electrodes 9 are made of a conductive material and have slits 9a extending in its axial direction. A plurality of cylindrical electrodes 9 are supported by the insulating substrate 1 in such a manner as being inserted into each cuts 3 so that the insulating substrate 1 is fitted into each slit 9a.

IPC 8 full level
H01R 33/76 (2006.01); **H01R 11/01** (2006.01)

CPC (source: EP US)
H01R 12/718 (2013.01 - EP US); **H01R 13/24** (2013.01 - EP US)

Citation (search report)

- [IY] US 2006009055 A1 20060112 - LI CHE-YU [US]
- [Y] US 2005266703 A1 20051201 - NODA ATSUHITO [JP], et al
- See references of WO 2009144812A1

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)
EP 2282381 A1 20110209; EP 2282381 A4 20111012; CN 102017333 A 20110413; JP 4940349 B2 20120530; JP WO2009144812 A1 20110929; US 2011006795 A1 20110113; US 8690584 B2 20140408; WO 2009144812 A1 20091203

DOCDB simple family (application)
EP 08777029 A 20080530; CN 200880129006 A 20080530; JP 2008060018 W 20080530; JP 2010514305 A 20080530; US 92165008 A 20080530